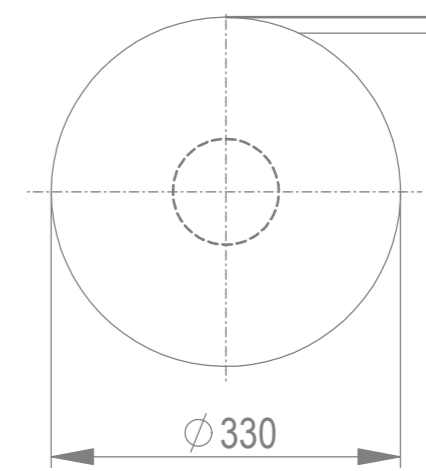
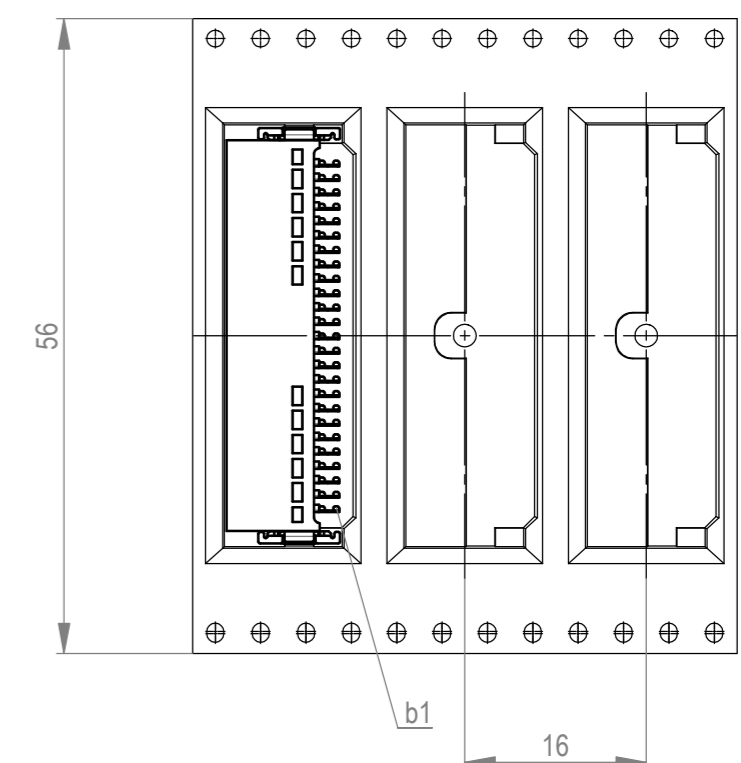


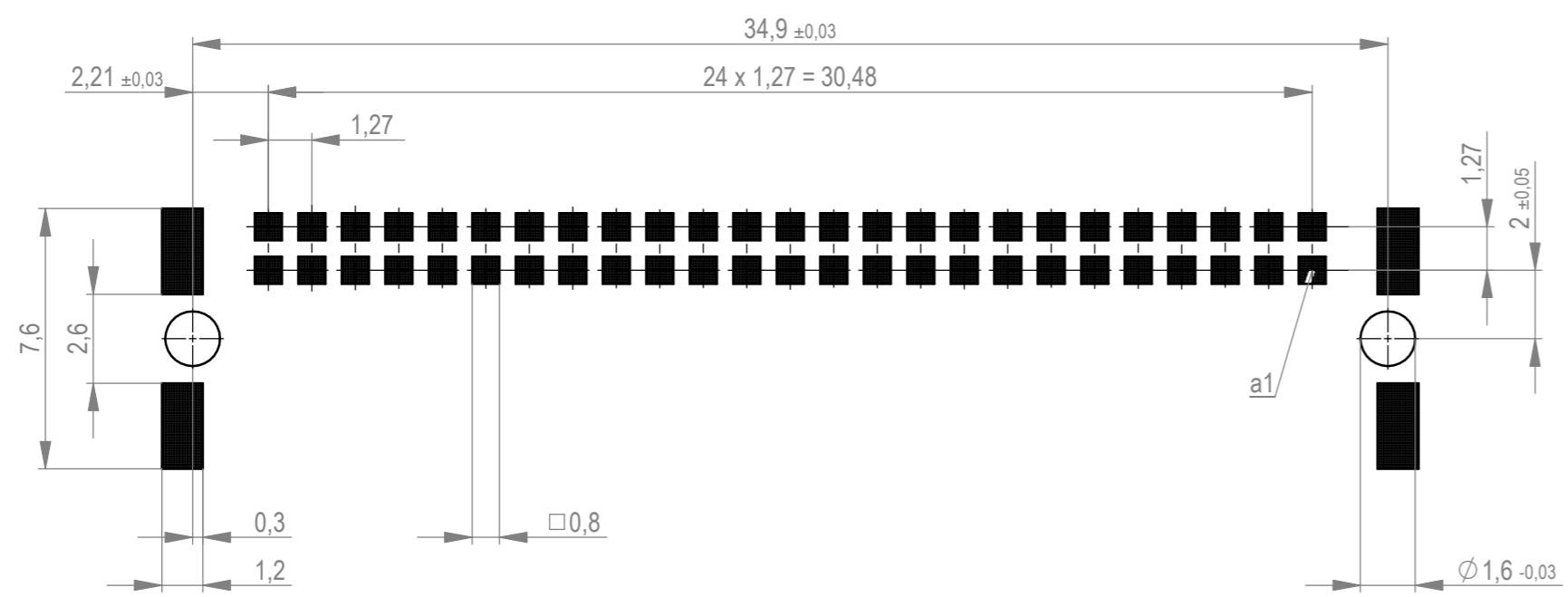
Verpackt im Gurt in Anlehnung an DIN IEC 60286-3  
 tape on reel packaging according to DIN IEC 60286-3  
 Verpackungseinheit: 560 Stück  
 packaging unit: 560 pcs



Abspulrichtung - reel off direction →



Leiterplatten-Layout Vorschlag für SMT  
 PCB-Layout Proposal for SMT



Anforderungsstufe 1  
 performance level 1

Kontaktbereich vergoldet  
 mating area gold plating

Anschlussbereich verzinkt 4-6 µm  
 terminal area 4-6 µm tin plating

Koplanarität der Anschlüsse ≤ 0,1 mm  
 coplanarity area of termination ≤ 0,1 mm

BA3-03 - Standard Bauhöhe  
 type3-03 - Standard Assembly Height

Dimension no.	Tolerances ISO 8015	All Dimensions in mm	Scale Material 5:1
Customer drawing: This Drawing is a controlled Document.	Subject to modification without prior notice. Drawing will not be updated.		Messlerl. SMC-B 50-SMD-BA3-03 Male SMC-B 50-SMT-type3-03
j1 Index	13.05.2023 Date	TE Connectivity	C A2
Class		SMCB	

Die deutsche Version dieser Zeichnung dient nur zur Erleichterung der Handhabung. Bei Abweichungen vom englischen Original gilt das englische Original. Any drawing that has been altered for convenience only and may deviate from the original. In case of any deviation the English version shall prevail.

单击下面可查看定价，库存，交付和生命周期等信息

[>>TE Connectivity\(泰科\)](#)